SILICON ULTRA-FAST RECOVERY EPITAXIAL RECTIFIER DIE

Applications:

• Switching Power Supply • Converters • Free-Wheeling Diodes • Polarity Protection Diode

Features:

- Glasspassivated Epitaxial Diode with Mesa Structure
- Soft Reverse Recovery at Low and High Temperature
- Low Forward Voltage Drop and Low Reverse Current
- Electrically and Mechanically Stable during and after Packaging

Maximum Ratings:

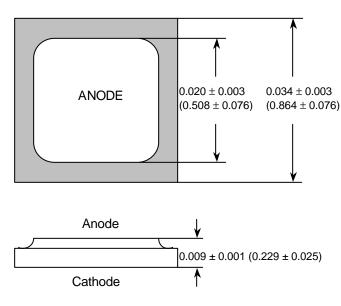
Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	V _{RWM}	-	400	V
Max. Output Current	Ι _ο	50% duty cycle, rectangular wave form; $T_A = 55$ °C	1.2	A
Max. Peak One Cycle Non- Repetitive Surge Current	I _{FSM}	8.3 ms, sine pulse ⁽¹⁾	20	A
Max. Junction Temperature	TJ	-	-55 to +175	°C
Max. Storage Temperature	T _{stg}	-	-55 to +200	°C
Reverse Recovery Time	t _{rr}	I _F =0.5A, I _R =1.0A, I _{RM} =0.25A	30	nS

Electrical Characteristics:

Characteristics	Symbol	Condition	Max.	Units
Max. Forward Voltage Drop	V _{F1}	2A, pulse, T _J = 25 °C	1.6	V
	V _{F2}	1.2A, pulse, T _J = 25 °C	1.4	V
Max. Reverse Current	I _{R1}	$V_R = V_{RWM}$, pulse, $T_J = 25 \ ^{\circ}C$	0.5	μA
	I _{R2}	$V_R = V_{RWM}$, pulse, $T_J = 150 \text{ °C}$	150	μA
Max. Junction Capacitance	CT	$V_{R} = 10V, T_{C} = 25 \ ^{\circ}C$	10	pF
		$f_{SIG} = 0.1$ to 1MHz,		
		$V_{SIG} = 50 \text{mV} \text{ (p-p)}$		

⁽¹⁾ in TO package

Mechanical Dimensions: In Inches (mm)



Bottom side metalization: Ti/Ni/Ag - 30 kÅ minimum.

Top side metalization: AI - 25 kÅ minimum

Bottom side is cathode, top side is anode.

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TECHNICAL DATA

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